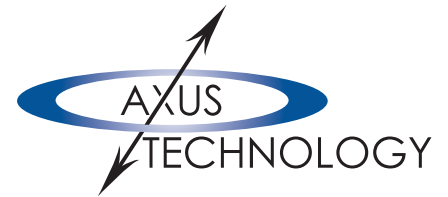


# Disco DFG8540



Your source for leading-edge surface processing solutions



Disco DFG8540 system is a fully automatic in-feed surface grinder. With its conventional two-spindle, three-chuck design, the DFG8540 is capable of performing both large diameter grinding and thin-finish grinding. The processing position of the grinding wheel coincides with the chuck table for each spindle for improved grinding performance.

## OPTIONS AVAILABLE

Vacuum system with automatic fluid separation unit

Temperature control system for stabilizing process results

## FEATURES

- Automated thinning up to 200mm diameter wafers
- Ultra-thin wafer handling to 100µm and less
- DBG option available and plasma-ready
- Flat/Notch alignment orientation
- Interior grind water nozzle
- Chuck/Spinner table
- Positioning and stopping system
- 2 air bearing grind spindles, 3 rotary-chuck tables



In-feed grinding w/wafer rotation